

Title (en)

SOLDER ALLOY AND SOLDER PASTE CONTAINING SAID ALLOY

Title (de)

LÖTLEGIERUNG UND LÖTPASTE MIT DIESER LEGIERUNG

Title (fr)

ALLIAGE DE BRASAGE ET PÂTE À BRASER CONTENANT LEDIT ALLIAGE

Publication

**EP 4025379 A1 20220713 (EN)**

Application

**EP 20761287 A 20200831**

Priority

- EP 19195895 A 20190906
- EP 2020074193 W 20200831

Abstract (en)

[origin: WO2021043708A1] The present invention relates to a lead-free solder alloy which consists essentially of or consists of: from 0.01 to 11 wt. % of zinc (Zn); from 0.01 to 6 wt.% of bismuth (Bi); from 0.01 to 2 wt.% of gallium (Ga); and, tin (Sn), wherein said weight percentages are based on the total weight of the alloy. The invention is also directed to a solder paste comprising the defined lead-free solder alloy in particulate form and a solder flux.

IPC 8 full level

**B23K 35/26** (2006.01); **B23K 35/02** (2006.01); **C22C 13/00** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP)

**B23K 35/025** (2013.01); **B23K 35/262** (2013.01); **C22C 13/00** (2013.01); **H05K 3/3463** (2013.01); **H05K 3/3485** (2020.08)

Citation (search report)

See references of WO 2021043708A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2021043708 A1 20210311**; CN 114340836 A 20220412; EP 4025379 A1 20220713

DOCDB simple family (application)

**EP 2020074193 W 20200831**; CN 202080062342 A 20200831; EP 20761287 A 20200831